ABSTRACT

COPPER WIRE FOR BONDING WIRE AND METHOD OF PRODUCING COPPER WIRE FOR BONDING WIRE

A copper wire for a bonding wire for forming a bonding wire is disclosed, in which the copper wire is formed of high-purity copper having a purity of 99.9999 mass% or more, a wire diameter of the copper wire is 0.5 mm to 3.5 mm, and an area ratio of a (001) plane in a cross-section of the copper wire perpendicular to a wire-drawing direction is 15% to 30%.

FIG.1